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TaichuPix-3 test

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Results of 4-layer flex boards

Flex num.	Chip pos.	Chip num.	Status	Min. ITHR
V1p4-A	U9 (bonding cut), U10	W1R8, W2R32	U10 work	U10: 32
V1p4-B	U9, U10	W1R7, W2R31	Work	U10: 64; U9: 96; U9&U10: 96
V1p4-C	U9, U10	W1R3, W1R2	Work	U10: 64; U9: 96; U9&U10: 96.
V1p4-D	U9, U10	W1R5, W1R4	Work	U10: 96; U9: 64; U9&U10: 96.
V1p4-E	U9, U10	W1R10, W1R9	Work	U10: 48; U9: 24; U9&U10: 64.
V1p4-F	U9, U10	W1R18, W1R16	Work	U10: 64; U9: 32; U9&U10: 96.
V1p4-Q	U1, U2	W1R14, W1R11	Work	U1: 48; U2: 32; U1&U2: 64&48.
V1p4-R	U1, U2	W1R22, W1R21	Work	U1: 32; U2: 32; U1&U2: 96&64.
V1p4-S	U1, U2	W1R26, W1R24	Work	U1: 32; U2: 64; U1&U2: 96&64.
V1p4-T	U1, U2	W1R28, W1R27	Work	U1: 32; U2: 32; U1&U2: 64&64.
V1p4-U	U1, U2	W1R33, W1R30	Work	U1: 64; U2: 48; U1&U2: 160&64.
V1p4-W	U1, U2	W1R34, W1R36	Work	U1: 48s; U2: 48; U1&U2: 96&96.

11 boards have 2 chips working, 1 board has 1 chip working

Results of 2-layer flex boards

Flex num.	Chip pos.	Chip num.	Status	Min. ITHR
V1p3-E	U4, U7		Current normal, no output	
V1p3-F	U4, U7		U7 work, power higher U4 short	U7: 160
V1p3-G	U5		Work	U5: 96
V1p3-H	U1, U2, U9, U10	U2 = W9R22	U9, U10 work at beginning, no output now; U1, U2 work	U1:128; U2: 96; U1&U2: 224&224
V1p3-I	U1, U2, U10		U10 work at beginning, no output several days later U1, U2 work	U10: 96 U1/U2:96, U1&U2: 176&160
V1p3-K	U1, U9, U10	U9 = W1R29	U10 work at begin., no output after U9 bonding, U9 work in OCT, no output to APULSE/Laser U1 work	U10: 96 U1:96, with ghost

- 2 boards have 2 chips working, 3 board has 1 chip working
- 3 boards work normally at the beginning, while show no output several days later
 - Damage of socket ?
 - Effect of storage condition ? i.e. humidity

Status of chips and flex

- **5 good chips available, 7 chips without wafer testing available**
- **New flex production expected to be finished this week**
 - 2-layer flex, 9 March
 - 4-layer flex, 11 March